

IN25AA080N, IN25AA080D, IN25AA160N, IN25AA160D

NONVOLATILE ELECTRICALLY ERASABLE PROM WITH SERIAL PERIPHERAL INTERFACE (SPI).

functionally compatible to 25AA080, 25AA160 (Microchip)

DESCRIPTION

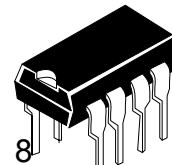
The IN25AA080N/D are a 8K(1Kx8) serial Electrically Erasable PROM with SPI interface.

The IN25AA160N/D are a 16K (2Kx8) serial Electrically Erasable PROM with SPI interface (SPI).

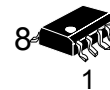
The ICs is purposed for reading, writing & nonvolatile data storage in electronic units with SPI interface. ICs are realized in SO-8 (MS-012AA) and DIP-8 (MS-001BA)

FEATURES

- Data capacity, Q_{INF} :
for IN25AA080N, IN25AA080D 8192 bit;
for IN25AA160N, IN25AA160D 16384 bit;
- Maximum clock frequency, f_C :
for $4,5\text{ V} \leq U_{CC} \leq 5,5\text{ V}$ 3 MHz;
for $2,5\text{ V} \leq U_{CC} \leq 5,5\text{ V}$ 2 MHz;
for $1,8\text{ V} \leq U_{CC} \leq 5,5\text{ V}$ 1 MHz;
- Maximum stand-by current, I_{CC} :
for $U_{CC} = 5,5\text{ V}$, $U_{IL} = 0\text{ V}$, $U_{IH} = U_{CC}$ 5,0 μA
for $U_{CC} = 2,5\text{ V}$, $U_{IL} = 0\text{ V}$, $U_{IH} = U_{CC}$ 1,0 μA ;
- Maximum read current, I_{OCCR} :
for $U_{CC} = 5,5\text{ V}$, $f_C = 3,0\text{ MHz}$, SO pin is not loaded1,0 mA,
for $U_{CC} = 2,5\text{ V}$, $f_C = 2,0\text{ MHz}$, SO pin is not loaded0,5 mA;
- Maximum write current, I_{OCCW} :
for $U_{CC} = 5,5\text{ V}$ 5,0 mA;
for $U_{CC} = 2,5\text{ V}$ 3,0 mA;
- Byte & page (16 bytes) data write modes are available;
- Endurance $N_{E/W}$,1000000 cycles;
- Build-in write protection block
- Write protection for 1/4, 1/2, or all of storage array;
- Power on/off data protection circuitry;
- Supply voltage U_{CC} 1,8 ... 5,5 V;
- Operating temperature range -40 ... +85°C.
- 100 years non-volatile data retention time



N SUFFIX
DIP

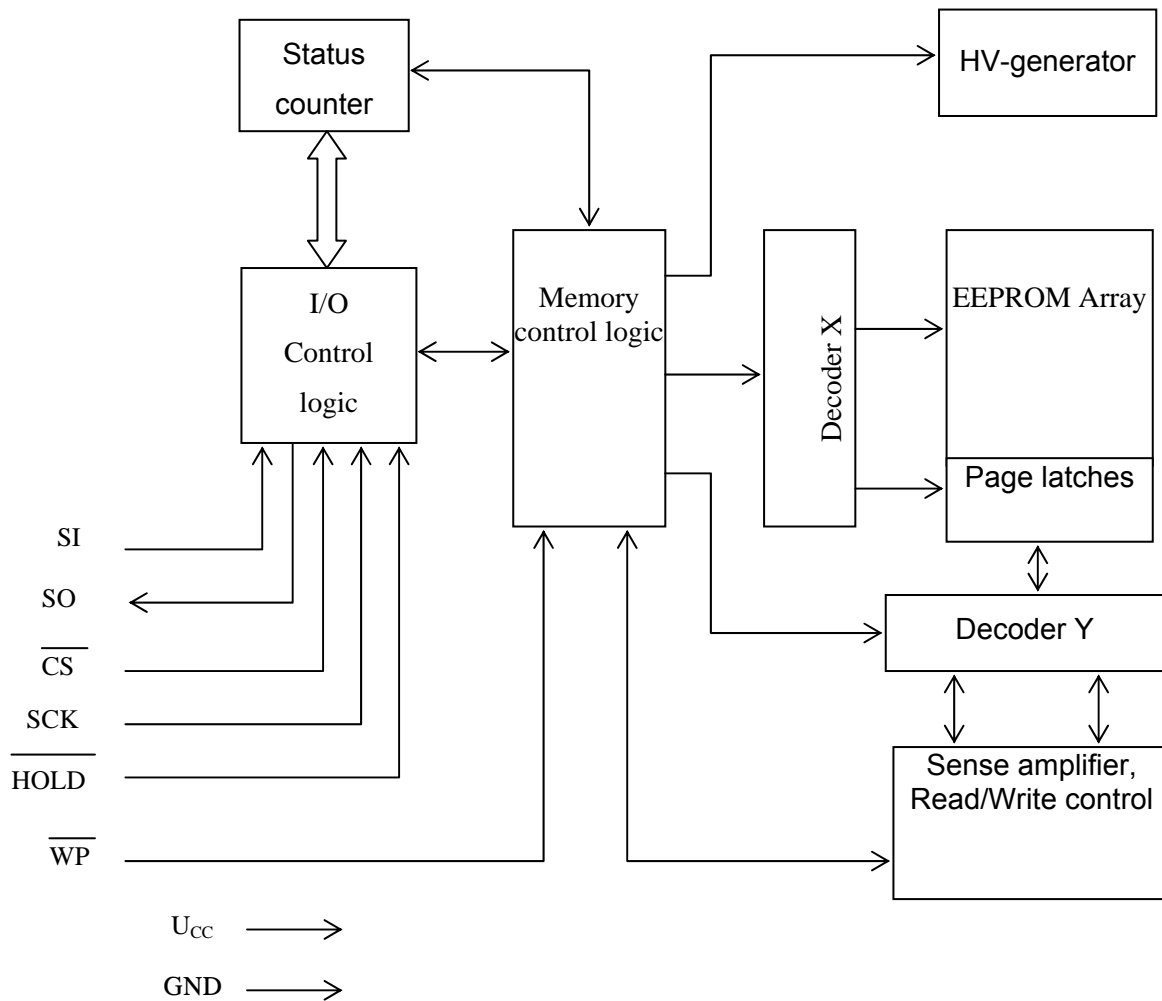


D SUFFIX
SOIC

PIN FUNCTIONS

Pin Name	Function
CS	Chip Select
SO	Serial Data Output
WP	Write protection
GND	Ground
SI	Serial Data Input
SCK	Clock Input
HOLD	Hold input *
V _{CC}	Power Supply

Block Diagram



Recommended Operation Conditions & Maximum Ratings*

Parameter, unit	Symbol	Recommended Operation Conditions		Maximum Ratings		
		Min	Max	Min	Max	
Supply voltage, V	U_{CC}	1,8	5,5	-0,6	7,0	
High level input voltage, V	U_{IH}	$2,7\text{ V} \leq U_{CC} \leq 5,5\text{ V}$	2,0	$U_{CC} + 1,0$	-	$U_{CC} + 1,0$
		$1,8\text{ V} \leq U_{CC} < 2,7\text{ V}$	$0,7U_{CC}$	$U_{CC} + 1,0$		
Low level input voltage, V	U_{IL}	$2,7\text{ V} \leq U_{CC} \leq 5,5\text{ V}$	-0,3	0,8	-0,6	-
		$1,8\text{ V} \leq U_{CC} < 2,7\text{ V}$	-0,3	$0,3U_{CC}$		
Ambient temperature	T_A	-40	85	-60	150	

ESD protection 2000 V.
 Input capacity C_i , output capacity C_o have to be not more than 7pF for $U_{CC} = 5,0\text{ V}$ & $T_A = (25 \pm 10)^\circ\text{C}$.

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Electric Parameters ($-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$)

Parameter, unit	Symbol	Mode	Min	Max	$T_A, ^{\circ}\text{C}$
Low level output voltage, V	U_{OL}	$2,5 \text{ V} \leq U_{CC} \leq 5,5 \text{ V}$ $I_{OL} = 2,1 \text{ mA}$	-	0,4	$25 \pm 10;$ $-45; 85$
		$1,8 \text{ V} \leq U_{CC} \leq 2,5 \text{ V}$ $I_{OL} = 1,0 \text{ mA}$	-	0,2	
High level output voltage, V	U_{OH}	$U_{CC} = 1,8 \text{ V}$ $I_{OH} = -400 \text{ uA}$	1,3	-	
		$U_{CC} = 5,5 \text{ V}$ $I_{OH} = -400 \text{ uA}$	5,0	-	
Low level input leakage current, uA	I_{ILL}	$U_I = 0 \text{ V}$	-	-10,0	
High level input leakage current, uA	I_{ILH}	$U_I = 5,5 \text{ V}$	-	10,0	
Low level output leakage current, uA	I_{OLL}	$U_I = 0 \text{ V}$	-	-10,0	
High level output leakage current, uA	I_{OLH}	$U_I = 5,5 \text{ V}$	-	10,0	
Consumption current, uA	I_{CC}	$U_{CC} = 5,5 \text{ V}, U_{IL} = 0 \text{ V}$ $U_{IH} = U_{CC}$	-	5,0	
		$U_{CC} = 2,5 \text{ V}, U_{IL} = 0 \text{ V}$ $U_{IH} = U_{CC}$	-	1,0	
Consumption current (Operating Read), uA	I_{OCCR}	$U_{CC} = 5,5 \text{ V}, f_C = 3 \text{ MHz}$ SO pin is not loaded	-	1,0	
		$U_{CC} = 2,5 \text{ V}, f_C = 2 \text{ MHz}$ SO pin is not loaded	-	0,5	
Consumption current (Operating Write), uA	I_{OCCW}	$U_{CC} = 5,5 \text{ V}, f_C = 3 \text{ MHz}$	-	5,0	
		$U_{CC} = 2,5 \text{ V}, f_C = 2 \text{ MHz}$	-	3,0	
Data access time on SCK transition to low level, ns	t_v	$4,5 \text{ V} \leq U_{CC} \leq 5,5 \text{ V},$ $f_C \leq 3 \text{ MHz}$	-	150	
		$2,5 \text{ V} \leq U_{CC} < 4,5 \text{ V},$ $f_C \leq 2 \text{ MHz}$	-	230	
		$1,8 \text{ V} \leq U_{CC} < 2,5 \text{ V},$ $f_C \leq 1 \text{ MHz}$	-	475	
Output disable time on $\overline{\text{CS}}$ high, ns	t_{DIS}	$4,5 \text{ V} \leq U_{CC} \leq 5,5 \text{ V},$ $f_C \leq 3 \text{ MHz}$	-	200	
		$2,5 \text{ V} \leq U_{CC} < 4,5 \text{ V},$ $f_C \leq 2 \text{ MHz}$	-	250	
		$1,8 \text{ V} \leq U_{CC} < 2,5 \text{ V},$ $f_C \leq 1 \text{ MHz}$	-	500	
Output disable time on $\overline{\text{HOLD}}$ low, ns	t_{HZ}	$4,5 \text{ V} \leq U_{CC} \leq 5,5 \text{ V},$ $f_C \leq 3 \text{ MHz}$	100	-	
		$2,5 \text{ V} \leq U_{CC} < 4,5 \text{ V},$ $f_C \leq 2 \text{ MHz}$	150	-	
		$1,8 \text{ V} \leq U_{CC} < 2,5 \text{ V},$ $f_C \leq 1 \text{ MHz}$	200	-	
Output enable time on $\overline{\text{HOLD}}$ high, ns	t_{HV}	$4,5 \text{ V} \leq U_{CC} \leq 5,5 \text{ V},$ $f_C \leq 3 \text{ MHz}$	100	-	
		$2,5 \text{ V} \leq U_{CC} < 4,5 \text{ V},$ $f_C \leq 2 \text{ MHz}$	150	-	
		$1,8 \text{ V} \leq U_{CC} < 2,5 \text{ V},$ $f_C \leq 1 \text{ MHz}$	200	-	
Write/Erase cycle, ms	t_{CY}	$U_{CC} = 4,5 \text{ V}, f_C = 3 \text{ MHz}$	-	5	
Program/erase cycles	N_{EW}	$U_{CC} = 5,0 \text{ V}$	1000000	-	

IN25AA080N, IN25AA080D, IN25AA160N, IN25AA160D

Instruction Set

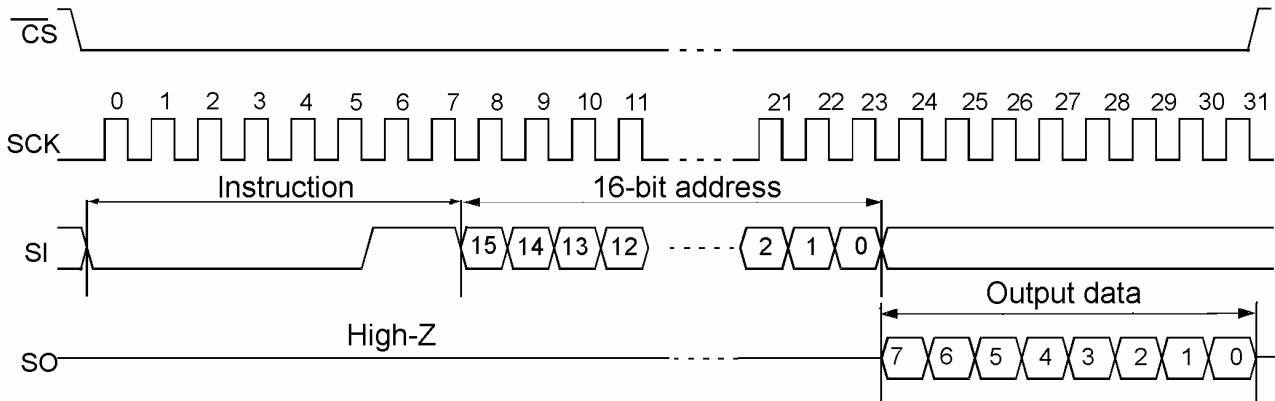
Instruction	Instruction Format	Description
READ	0000 X011	Read data from memory array beginning at selected address
WRITE	0000 X010	Write data to memory array beginning at selected address
WRDI	0000 X100	Reset the write enable latch (disable write operations)
WREN	0000 X110	Set the write enable latch (enable write operations)
RDSR	0000 X101	Read status register
WRSR	0000 X001	Write status register
Notes		
1 X – Any level (low or high).		

SPI parameters (-40 °C ≤ Ta ≤ 85 °C)

Sym bol	Parameter, unit	Mode	1,8 V ≤ U _{CC} < 2,5 V		2,5 V ≤ U _{CC} < 4,5 V		4,5 V ≤ U _{CC} ≤ 5,5 V	
			Min	Max	Min	Max	Min	Max
f _C	Clock frequency, MHz	C _L = 100 pF	-	1	-	2	-	3
t _{CSS}	CS setup time, ns		500	-	250	-	100	-
t _{CSH}	CS hold time, ns		475	-	250	-	150	-
t _{SU}	SI setup time, ns		50	-	50	-	30	-
t _{HD}	SI hold time, ns		100	-	100	-	50	-
t _{CSD}	Disable time on \overline{CS} , ns		Not less 500					
t _R	SCK rise time, us		Not more 2					
t _F	SCK fall time, us		Not more 2					
t _{HI}	SCK high time, ns		475	-	230	-	150	-
t _{LO}	SCK low time, ns		475	-	230	-	150	-
t _{CLD}	Clock delay, ns		Not less 50					
t _{CLE}	Clock setup time, ns		Not less 50					
t _{HO}	Data hold time, ns		Not less 0					
t _{HS}	\overline{HOLD} setup time, ns		200	-	100	-	100	-
t _{HH}	\overline{HOLD} hold time, ns		200	-	100	-	100	-

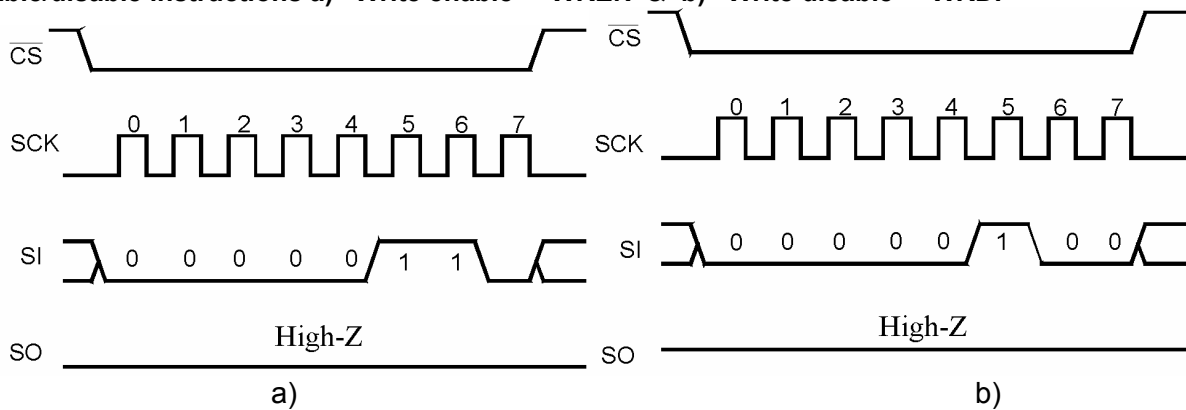
IN25AA080N, IN25AA080D, IN25AA160N, IN25AA160D

Data read sequence



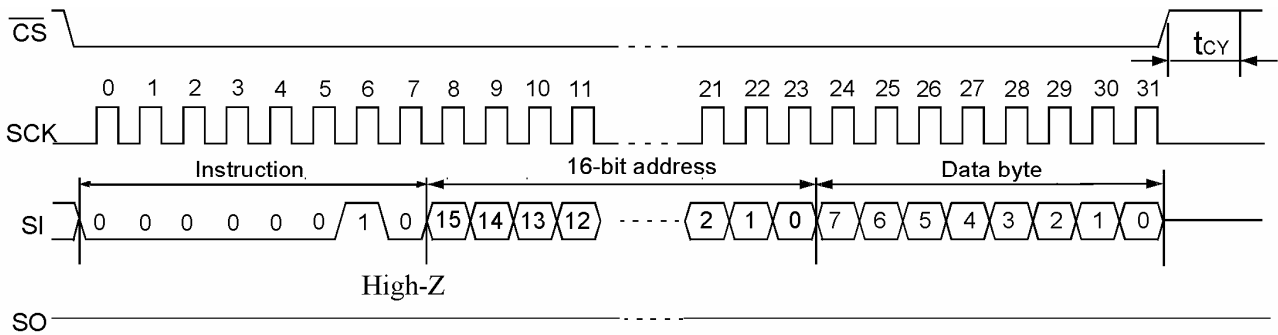
There are six 8-bit instructions available for executing of read/write operation. The feature of IN25AA080N, IN25AA080D (IN25AA160N, IN25AA160D) is that 6 (5) higher address bits are insignificant (have to be ignored).

Enable/disable instructions a) "Write enable" - WREN & b) "Write disable" - WRDI

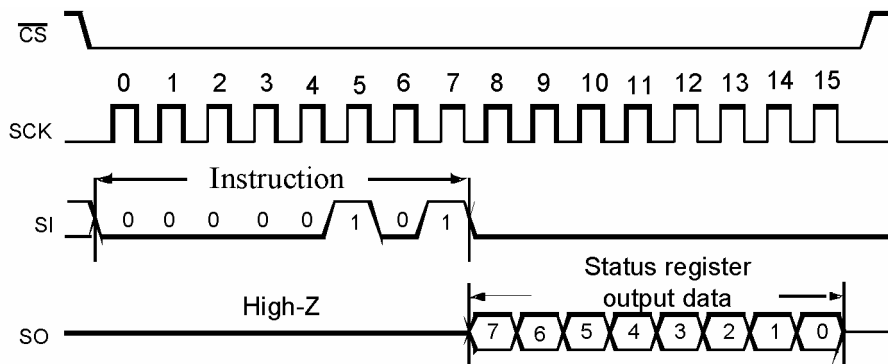


The powers up set ICs in the write disable state. For writing operation after power-up or after an WRDI (write disable) instruction, WREN (write enable) instruction must be issued. Any read/write operation can be executed on condition $\overline{CS} = 0$ (enable signal), high level on \overline{CS} pin switch IC to standby mode. Already initiated programming cycle will be completed independently from \overline{CS} signal. A low to high transition on \overline{CS} after a valid write sequence initiates an internal write cycle.

Byte write sequence



Read status register sequence



The RDSR (read status register) instruction provides access to the status register. The status register may be read at any time, even during a write cycle.

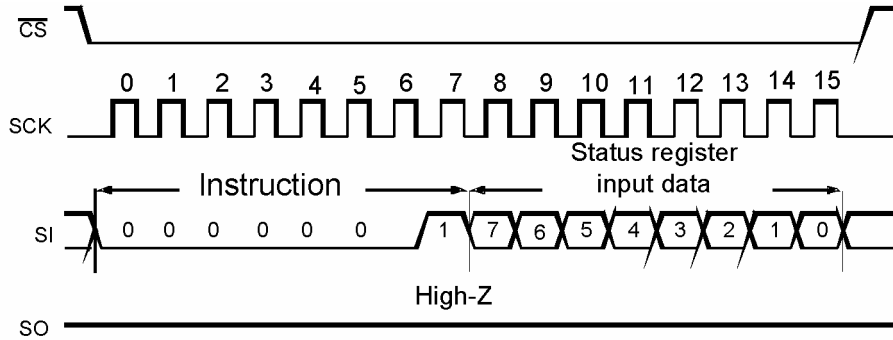
The 0th bit - WIP bit (Write-In-Process) of the status register indicates whether the IC is busy with a write operation. When set to a '1' a write is in progress, when set to a '0' no write is in progress. This bit is read only.

The 1st bit - WEL bit (Write Enable Latch) of the status register indicates the status of the write enable latch. When set to a '1' the latch allows writes to the array, when set to a '0' the latch prohibits writes to the array. This bit is read only.

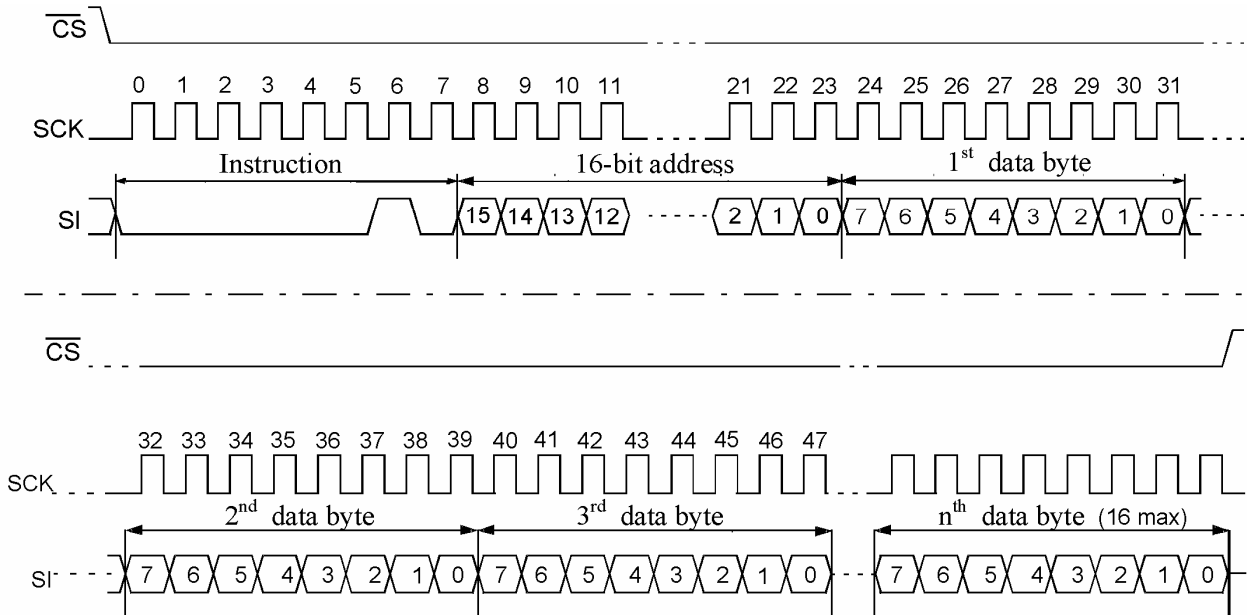
The 2nd & 3rd bits - BP0 and BP1 bits (Block Protection) indicate which blocks are currently write protected. These bits are set by the user issuing the WRSR instruction.

The SCK is used to synchronize the communication between a master and the IC. Instructions, addresses, or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

Write status register sequence

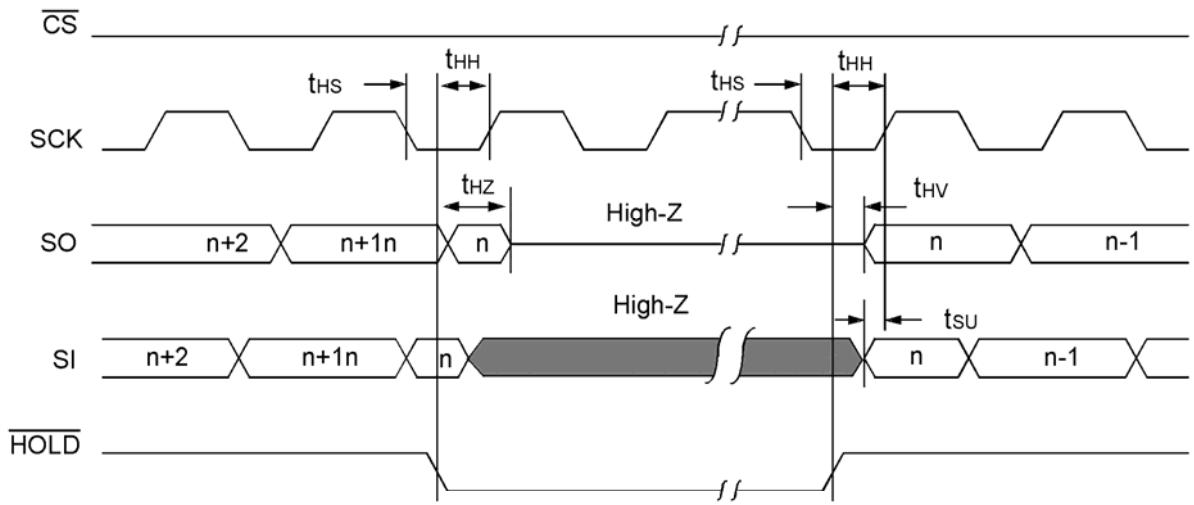


Page write sequence

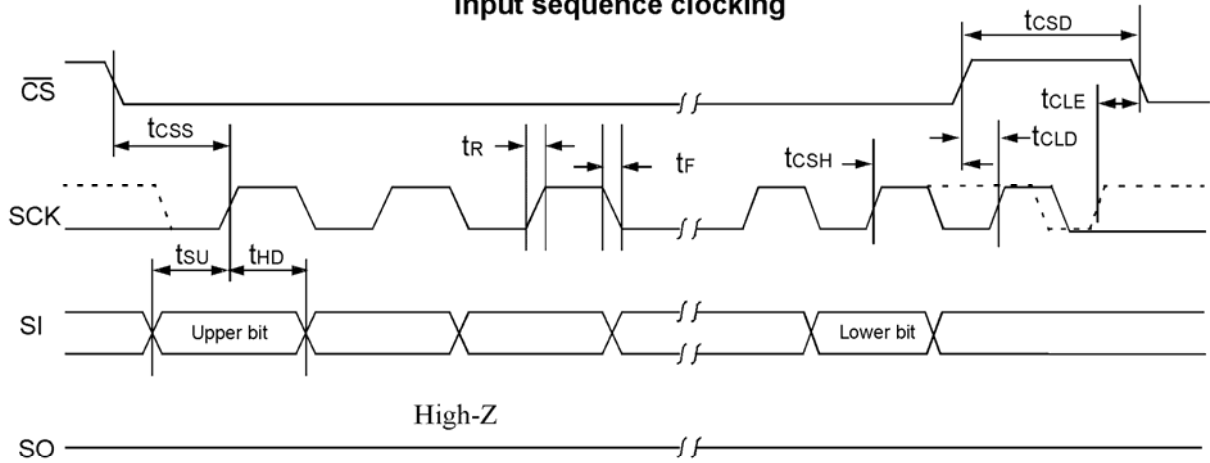


Data clocking diagramm

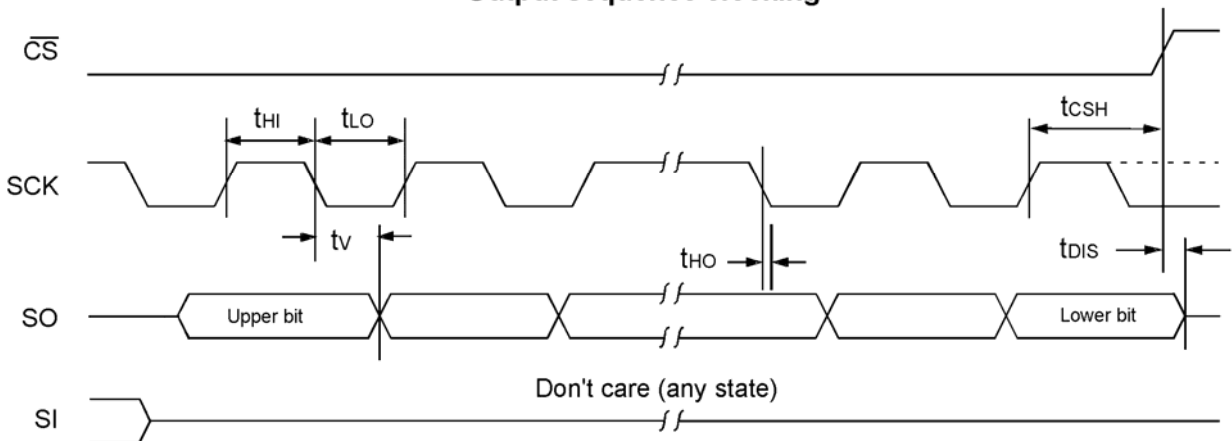
HOLD signal clocking



Input sequence clocking

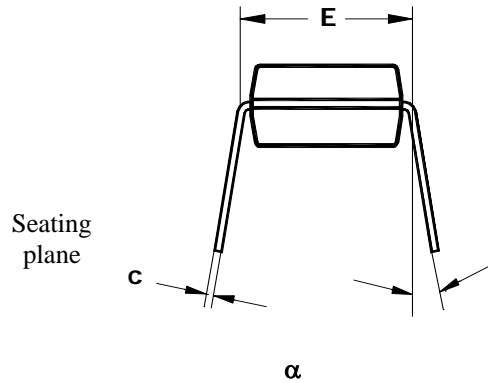
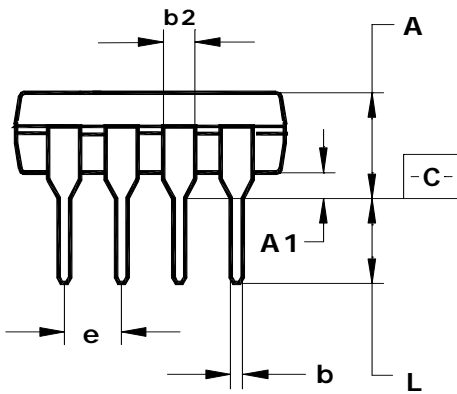
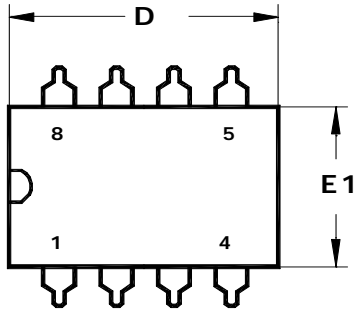


Output sequence clocking



IN25AA080N, IN25AA080D, IN25AA160N, IN25AA160D

N SUFFIX PLASTIC DIP
(MS-001BA)

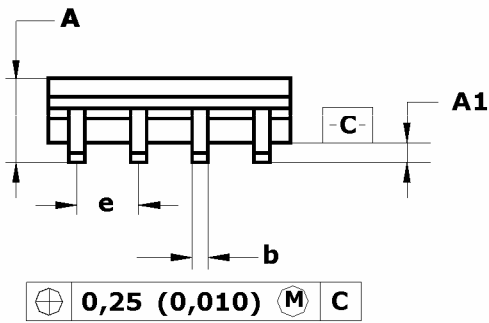
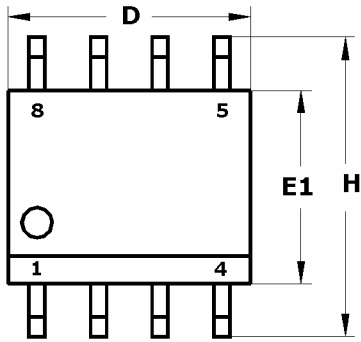


⊕ 0,25 (0,010) Ⓜ C

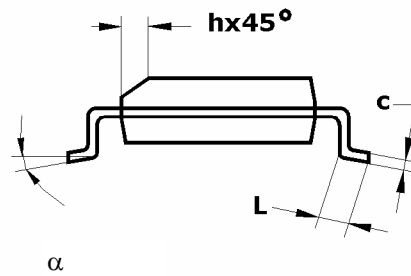
	D	E1	A	b	b2	e	α	L	E	c	A1
mm											
min	9.02	6.07	—	0.36	1.14		0°	2.93	7.62	0.20	0.38
max	10.16	7.11	5.33	0.56	1.78	2.54	15°	3.81	8.26	0.36	—
inches											
min	0.355	0.240	—	0.014	0.045		0°	0.115	0.300	0.008	0.015
max	0.400	0.280	0.210	0.022	0.070	0.1	15°	0.150	0.325	0.014	—

IN25AA080N, IN25AA080D, IN25AA160N, IN25AA160D

D SUFFIX PLASTIC SOP
(MS-012AA)



Seating plane



	D	E1	H	b	e	α	A	A1	c	L	h
mm											
min	4.80	3.80	5.80	0.33		0°	1.35	0.10	0.19	0.41	0.25
max	5.00	4.00	6.20	0.51	1.27	8°	1.75	0.25	0.25	1.27	0.50
inches											
min	0.1890	0.1497	0.2284	0.013		0°	0.0532	0.0040	0.0075	0.016	0.0099
max	0.1968	0.1574	0.2440	0.020	0.100	8°	0.0688	0.0090	0.0098	0.050	0.0196